



Investor Presentation

June 2023

Disclaimer

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.

01

Introduction

02

Q1 2023 and Outlook 2023

03

Ambition 2030



SUSS MicroTec at a glance



- Hidden champion headquartered in Germany with 70+ year track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: more than € 400 million revenue and >15% EBIT margin

SUSS is part of our digital life!

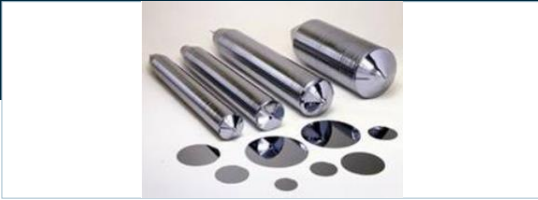
Our corporate vision defines our strategies

SUSS MicroTec Vision

**Leader in enabling innovative
advanced backend & photomask
solutions.**

Our world are the semiconductor frontend and backend process steps

Wafer fabrication



Front-end-of-line

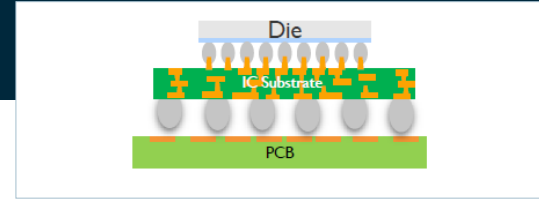
Wafer process



- Deposition/coating
- Cleaning
- **Patterning/lithography**¹
- Etching
- Implantation
- Annealing
- **Permanent bonding**
- **Temporary bonding**
- CMP polishing

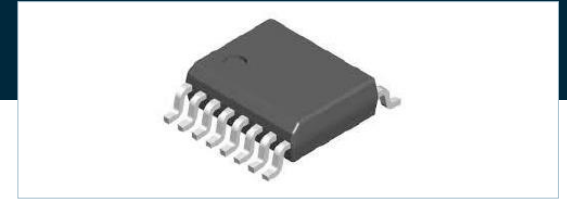
From middle-of-line to back-end-of-line

Advanced packaging



- Deposition/coating
- Cleaning
- **Patterning/lithography**
- Etching
- Annealing
- CMP polishing
- **Permanent bonding**
- **Temporary bonding**
- **Wafer-level packaging**
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

¹ Only related to Photomask processing

Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Advanced Backend Solutions as core asset in our product portfolio

Frontend

Advanced backend

Components

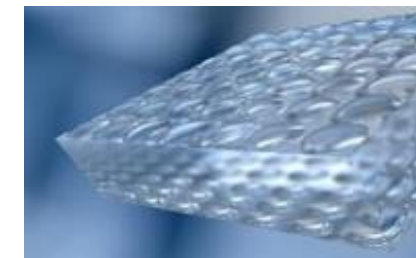
Segments Photomask Equipment



Advanced Backend Solutions¹



MicroOptics



Products

Photomask Equipment



MaskTrack X

Imaging

Mask Aligner
MA200/300



Projection
Scanner
DSC300

Coating



ACS300

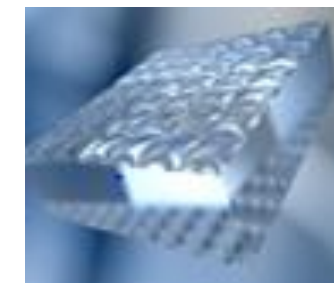
Bonding

XBC300



XB8

Microlens Arrays



Microlens Arrays

1) Business units Lithography and Bonder were merged into the new Advanced Backend Solutions business unit at the end of 2022. We will report in the new structure from the 2023 financial year onwards.

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Dynamic order momentum, but targeted margins not yet achieved in Q1 2023

Financial Results

Q1 2023

99.6

in € million

Order Entry
Q1 2023

70.4

in € million

Sales
Q1 2023

33.1

in %

Gross profit margin
Q1 2023

4.1

in %

EBIT Margin
Q1 2023

**Guidance for all three key
financial indicators confirmed**

Business Highlights Q1 2023



- Order entry remains strong despite generally expected slowdown in orders from semiconductor industry
- Sales up by 11.2% compared to last year; Photomask Solutions as main growth driver (business almost tripled)
- Challenging margin situation in Q1 2023, but better product mix and higher sales volume expected during the course of the year 2023
- Change in cost allocation from Q1 2023 onwards: costs for application centers shifted from SGA to R&D costs with an expected effect of ~ € 6 million in 2023
- Status of main R&D projects: integrated D2W hybrid bonder and wafer cleaner currently being installed at Sternenfels application center; first customer demonstrations are most likely to be carried out in the third quarter of 2023

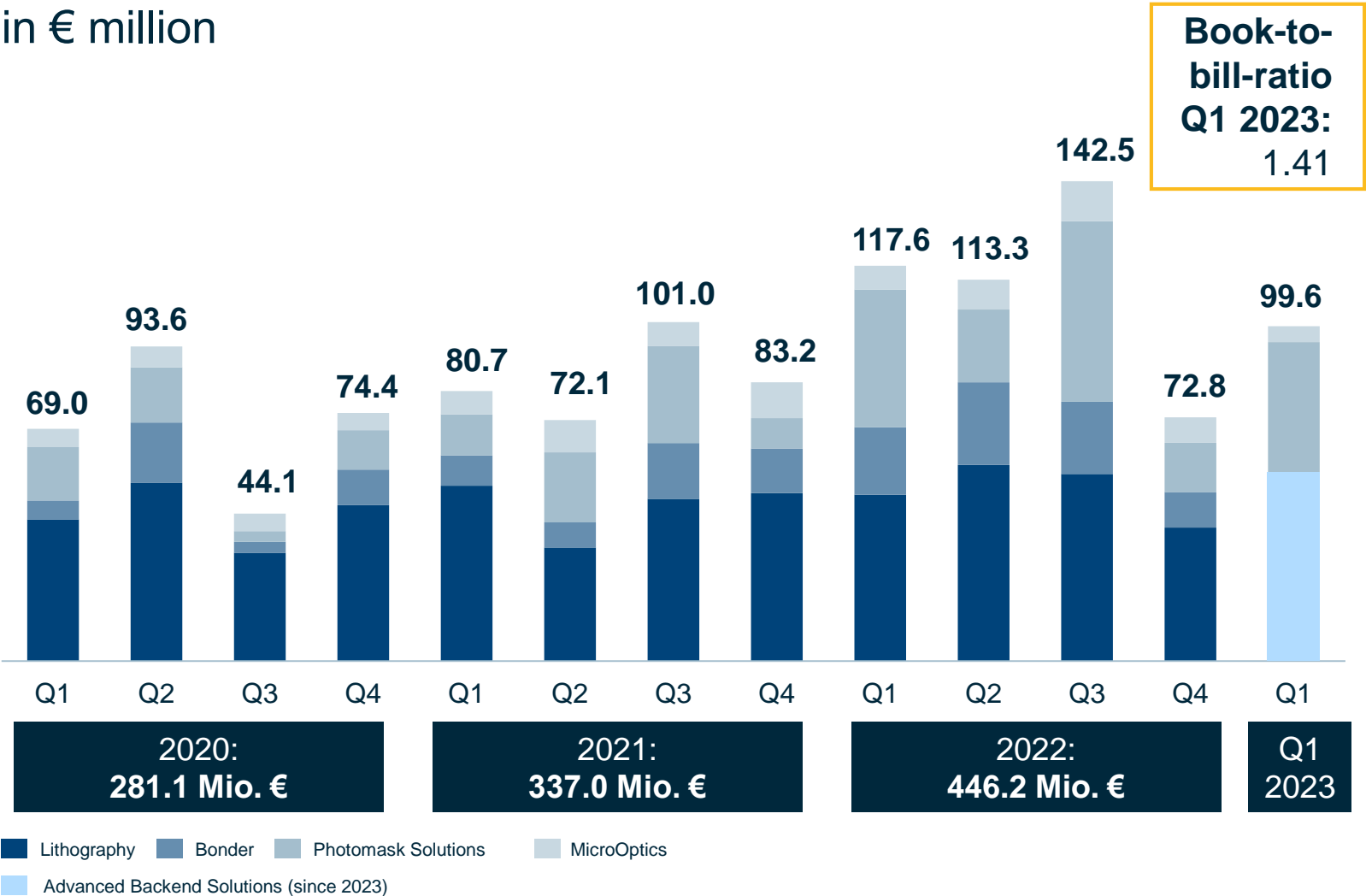
Strong order entry exceeded market expectations

In € million	Q1 2023	Q1 2022	Change
Order entry	99.6	117.6	-15.3%
Order backlog as of March 31	373.2	249.2	49.8%
Sales	70.4	63.3	11.2%
Gross profit	23.3	21.0	10.8%
Gross profit margin	33.1%	33.2%	-0.1%pts
EBIT	2.9	2.1	38.1%
EBIT margin	4.1%	3.3%	0.8%pts
Earnings after tax	2.1	1.4	50.0%
Earnings per share, basic (in €)	0.11	0.07	57.2%
Net cash	41.0	35.2	16.5%
Free Cashflow	0.3	1.6	-81.3%
Employees as of March 31	1,261	1,194	5.6%

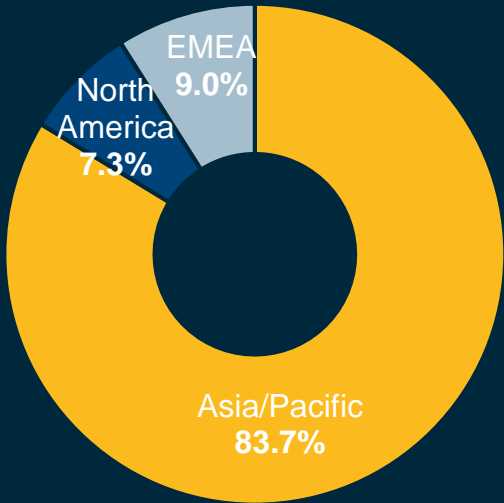
- **Strong order entry and order backlog** remain a solid foundation for targeted growth in 2023 and beyond
- **Absolute gross profit and EBIT increased yoy**
- **Gross profit margin and EBIT margin within own expectation but not yet at target**, mainly because of low margins in the bonder product lines and in MicroOptics
- Company has again created **value for shareholders** in Q1 2023 (earnings per share +57.2%)
- **Net cash position increased** once again due to higher prepayments

Order Entry by Division and Region

Order Entry by Division in € million



Order Entry by Region Q1 2023



Division Overview Q1 2023

Advanced Backend Solutions

in € million	Q1 2023	Q1 2022
Order entry	56.2	69.5
- thereof Lithography	44.8	49.4
- thereof Bonder	11.4	20.1
Total sales¹	41.0	45.5
- thereof Lithography	32.6	33.4
- thereof Bonder	8.4	12.1
Gross profit	14.9	15.9
Gross profit margin	36.3%	34.9%
EBIT	0.7	3.5
EBIT margin	1.7%	7.7%

- Decrease in order entry, mainly due to bonders and slightly lower demand for coaters; slight increase in orders for mask aligners
- Sales decreased by 9.9 percent because of lower sales level for automated permanent bonding systems compared to last year
- Gross profit margin increased due to good lithography margin
- Low EBIT margin as a result of low sales level and challenging bonder margins; higher R&D expenses for investments in future growth (especially hybrid bonding)

Photomask Solutions

in € million	Q1 2023	Q1 2022
Order entry	38.6	40.9
Total sales¹	23.1	7.8
Gross profit	7.0	2.1
Gross profit margin	30.3%	26.9%
EBIT	3.7	-1.4
EBIT margin	16.0%	-17.9%

- Order entry remains on a high level
- Strong sales growth because of high backlog and ongoing strong demand in Asia
- Gross profit and EBIT margin improved strongly because of high sales level and a good product mix

MicroOptics

in € million	Q1 2023	Q1 2022
Order entry	4.7	7.1
Total sales¹	6.9	10.6
Gross profit	1.4	3.1
Gross profit margin	20.3%	29.2%
EBIT	-1.1	0.7
EBIT margin	-15.9%	6.6%

- Q1 2023 saw a slow down in industrial applications
- Highly competitive automotive business
- Order entry and sales declined because of lower volume and price decreases from automotive customers
- Gross profit and EBIT declined accordingly

1) Total sales include internal sales (sales to other divisions) since 2021; gross profit margin and EBIT margin are calculated on the basis of total sales.

We expect to improve our three key performance indicators in 2023

Our Guidance 2023

We aim to take the next step on the way to our 2025 goals.



1) From 2023, we will use gross profit margin instead of free cash flow as the third performance indicator. For further information, please refer to the Annual Report.

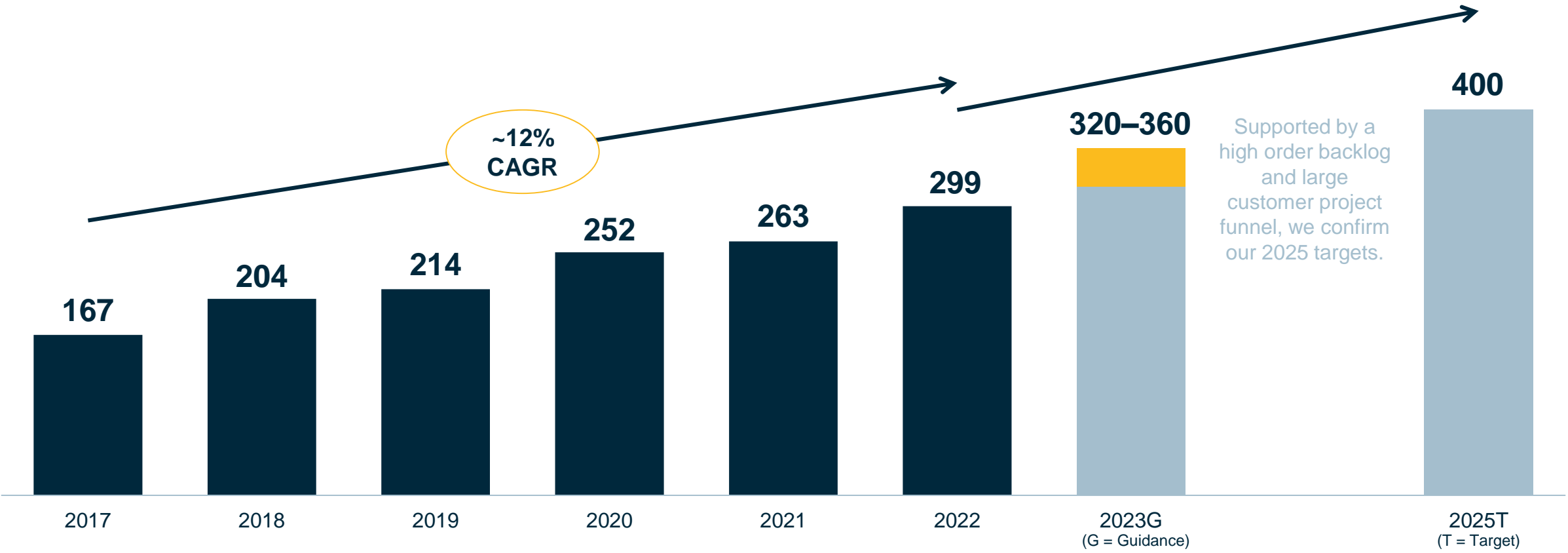
2) Including one-off effects of € 3.1 million. Operating EBIT margin thus accounted to 9.9%.

We aim to take the next step on the way to our 2025 goals

Our target 2025

Revenue of € 400 million with an EBIT margin of 15%

Confirmed



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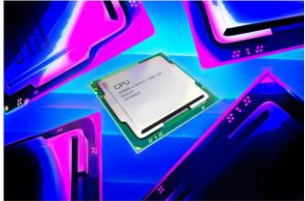
03

Ambition 2030

Granted investment in global chip factories boosts semi equipment industry



Biden signs \$280 billion CHIPS and Science Act



/ The bill includes \$52 billion in semiconductor subsidies

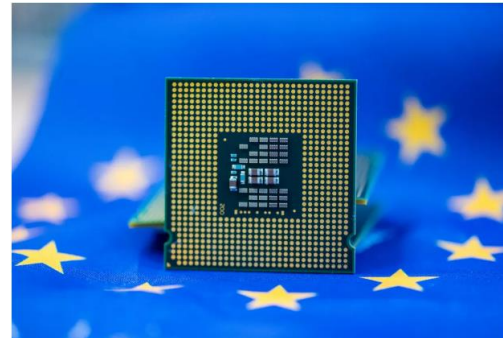
By MAKENA KELLY / @makemken
Aug 9, 2022, 4:07 PM EDT | 12 Comments / 0 New



TECHSPOT

The EU Chips Act: €43 billion to build a new European chipmaking industry

After the US, the European Union is working on its own Chips Act
By Alfonso Manuella December 6, 2022 at 7:42 AM | 11 comments



asia financial

Home AF Indexes Markets Fintech Energy Transport Health Regions

Semiconductors

China Seen Planning \$143 Billion Push to Boost Local Chipmakers

December 13, 2022

China plans a massive package to support its computer chip sector and will reportedly outlay over \$143 billion over five years

f t



Bloomberg

Technology

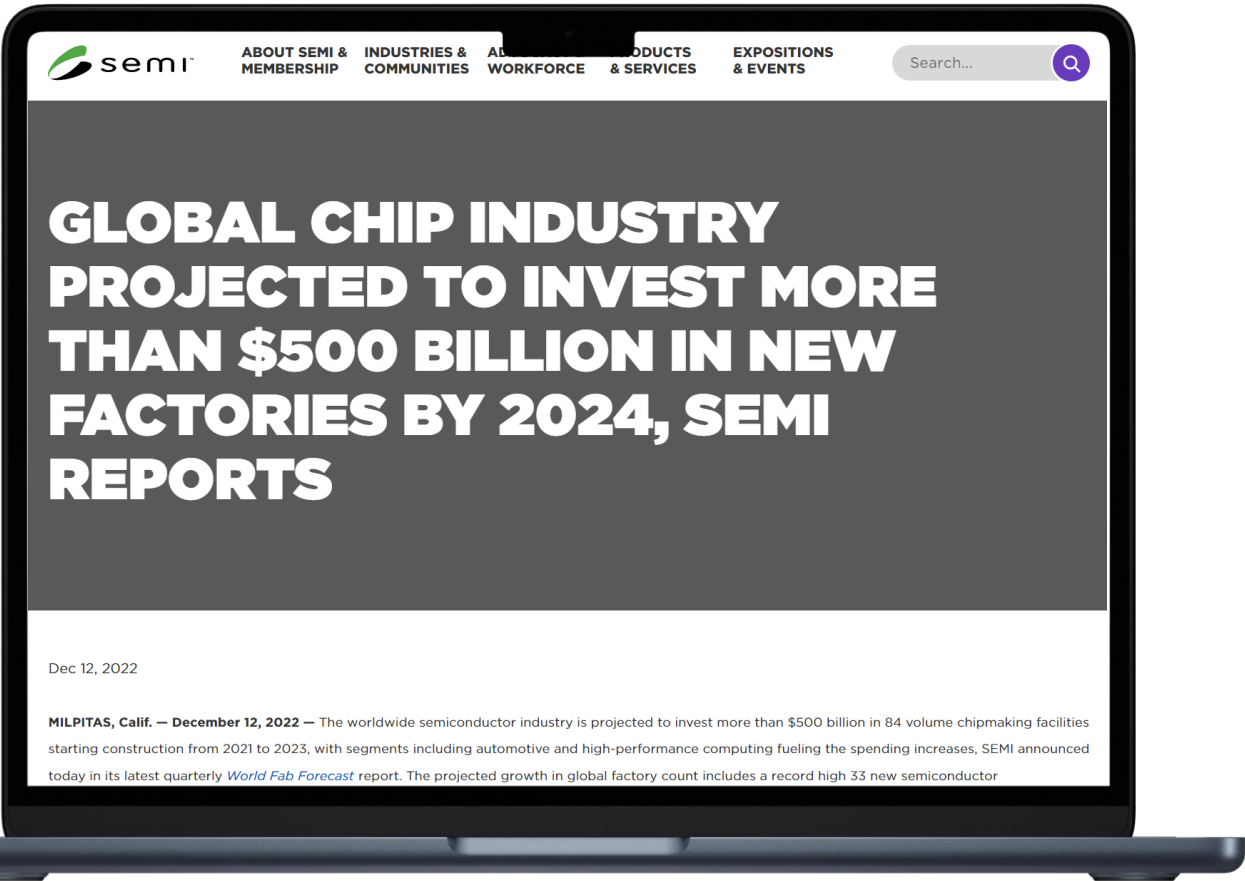
Taiwan Passes Its Chips Act, Offers Tax Credits to Chipmakers

- A quarter of chip firms' R&D expenses can be deducted from tax
- Major governments are racing to build chip plants at home

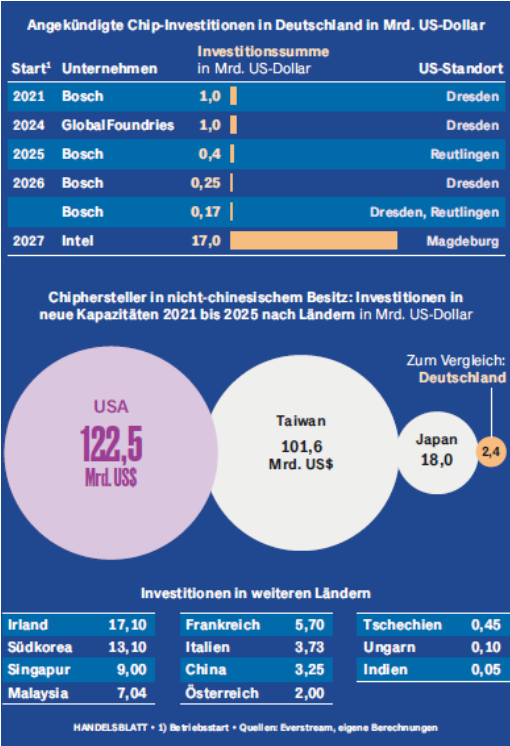
By Debby Wu

9. Januar 2023 um 03:26 MEZ Updated on 9. Januar 2023 um 06:04 MEZ

Mid-term investment of the semiconductor industry is well filled



Mega-Investments			
Angekündigte Chip-Investitionen in den USA in Mrd. US-Dollar			
Start ¹	Unternehmen	Investitionssumme in Mrd. US-Dollar	US-Standort
2021	NXP	0,1	Arizona
2022	Wolfspeed	1,0	New York
	Texas Instruments	3,5	Texas
	On Semi	0,4	New York
	Infineon	0,7	Texas
2023	Texas Instruments	3,5	Texas
	Intel	3,5	New Mexico
	GlobalFoundries	1,0	New York
2024	Intel	10,0	Arizona
	TSMC	12,0	Arizona
	Intel	10,0	Arizona
	Samsung	17,0	Texas
	Texas Instruments	3,5	Texas
	Wolfspeed	1,3	North Carolina
	Wolfspeed	5,0	North Carolina
2025	SK Hynix	15,0	TBD
	Micron	15,0	Idaho
	Texas Instruments	3,5	Texas
	Intel	10,0	Ohio
	Intel	10,0	Ohio
2026	TSMC	28,0	Arizona
2027	SK Siltron	0,6	Georgia



Summary of our strategic directives



Imaging Systems

- Mask Aligner
- Scanner
- Imprint

→ Maintain business volume by increasing share and higher scanner penetration (against stepper)

→ Gaining market share



Coating Systems

- Coater (Spin, Spray)
- Inkjet

→ Growth in line with the market

→ New growth opportunities with disrupting solution



Bonding Systems

- Temporary Bonding
- Permanent Bonding
(incl. Hybrid Bonding)

→ Growth in line with the market

→ Gaining market share

→ New growth opportunities with disrupting solution



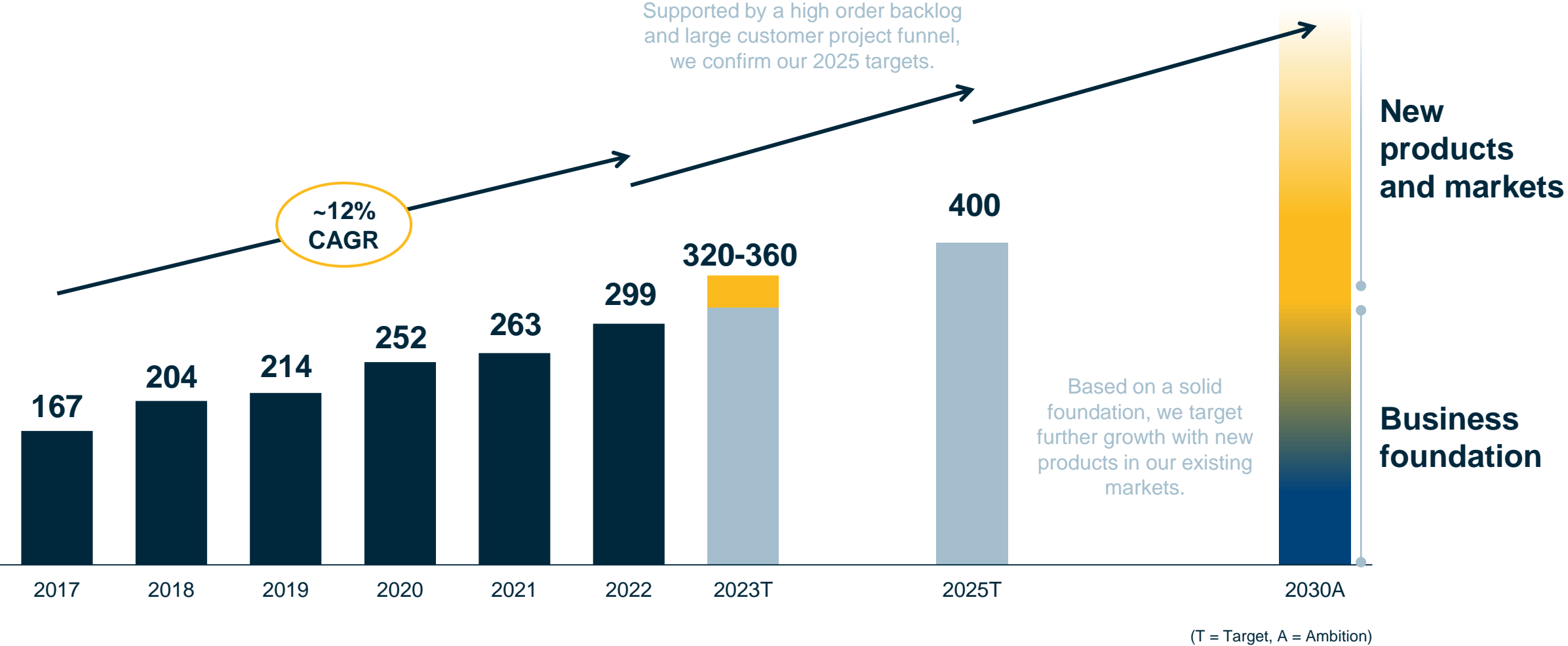
Photomask Equipment

- Photomask Equipment
- Wafer Cleaning

→ Growth in line with the market

→ New growth opportunities with disrupting solution

Based on our business foundation we see further potential beyond



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Financial Calendar



March 31
Annual Report 2022



May 11
Q1 Report 2023



May 31
Annual General Meeting 2023



August 3
Half Year Report 2023



November 9
Nine Months Report 2023

Enabling semiconductor innovations.
Creating solutions for the future.